

PROBING FIXTURE AND METHOD FOR SEMICONDUCTOR WAFER

Abstract of the Disclosure

A semiconductor wafer is placed into a probe fixture with a front side of the wafer facing up. Power and signal probes are then placed on an integrated circuit (IC) formed on the front side of the wafer. The probe fixture is retained at a test station either in an upright or an inverted position for testing and optical failure analysis. The probe fixture includes a position adjustment mechanism to locate the entire probe above the wafer and to more precisely position a tip of the probe on the IC. Optical failure analysis techniques are performed on the front side or the back side of the wafer while the wafer is retained in the test fixture and the probes are connected to the IC.